

**IN THE CLAIMS:**

Please cancel claim 15 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claim 13 as follows:

**LISTING OF CURRENT CLAIMS**

Claims 1-12. (Canceled)

Claim 13. (Currently Amended) A multi-chip package combining wire-bonding and flip-chip configuration comprising:

- a) a substrate having an upper substrate surface and a lower substrate surface, the upper substrate surface having a plurality of contact pads;
- 5 b) at least one wire bonding chip connected to the upper substrate surface and electrically connected to the substrate by a plurality of bonding wires;
- c) a molding compound having:
  - 10 i) a body formed on the upper substrate surface ~~covering~~ encapsulating each of the at least one wire bonding chip and the plurality of bonding wires, ~~the molding compound having:~~ wires;
  - 15 ii) ~~two extensions;~~ extensions extending from the body and along a horizontal direction on the substrate, the two extensions are substantially orthogonal; and
  - 20 iii) at least one recession having on arch shape and being located between the two extensions, the two extensions being spaced apart from the plurality of contact pads; and pads located on the upper substrate; and
- d) at least one flip-chip electrical device having a plurality of bumps electrically connected to the plurality of contact pads of the substrate.

Claim 14. (Previously Presented) The multi-chip package according to claim 13, wherein the distance between the at least one recession and a closest contact pad of the plurality of contact pads is greater than 1.0mm.

Claim 15. (Canceled)

Claim 16. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one recession has a shape of a quarter of a circle.

Claim 17. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one recession includes two recessions, the two recessions are symmetrical.

Claim 18. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has an U-shape.

Claim 19. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has an L-shape.

Claim 20. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one flip-chip electrical device is selected from a group consisting of a BGA package, a chip scale package, and a flip chip.

Claim 21. (Previously Presented) The multi-chip package according to claim 13, further comprising a plurality of solder balls located on the lower substrate surface.

Claim 22. (Previously Presented) The multi-chip package according to claim 13, further comprising a heat sink connected to the molding compound and the at least one flip-chip electrical device.

Claim 23. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has at least one step located on a surface opposite the substrate.

Claim 24. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has at least one indentation located on a surface opposite the substrate.

Claim 25. (Previously Presented) The multi-chip package according to claim 13, wherein the substrate has a molding gate metal layer.